© Copy	rial Composition right 2005. IPC, Bar ional and Pan-Ameri	nockburn, Illinois.	All rights reserved u entions.	under both level	documen l parts, the	nt is a declara e declaration	tion of the su encompasses	ubstances s all lowe	within the manufac level materials for	turer listed i which the r	item. No nanufac	ote: if the turer has	item is an as engineering i	sembly with lowe responsibility.	
					a Type * Declaration Class * ibute Class 6 - RoHS Yes/No, Homogeneous Mater					erials and M	ials and Mfg Information				
Supplier Information															
Company name*	Company u	Company unique ID			Unique ID Authority					Response Date*					
onsemi									2024-05	2024-05-17					
Contact Name	Title - Con	Title - Contact			Phone - Contact*				Email -	Email - Contact*					
Product-Env-Stewards	Product En	Product Enviro Compliance			NA				Produc	Product-Env-Stewards@onsemi.com					
Authorized Representative*	Title - Rep	Title - Representative			Phone - Representative*				Email -	Email - Representative*					
Product-Env-Stewards		Product En	Product Enviro Compliance			NA				Produc	Product-Env-Stewards@onsemi.com				
Requester Item Nu	Requester Item Number Mfr Iter		n Number Mfr Item Name		I	Effective Date	e Version	N	Ianufacturing Site		Weight	*	UOM	Unit Type	
	NCP718BSN330T1G 3		300 mA Low Iq, Wide Input Voltage LDO - TSOT23-5; 3V3 HZ		LDO - 2	2024-05-17		1	ТНВ		12.52		mg	Each	
Manufacturing Procces	s Information														
Terminal Plating / C	Plating / Grid Array Material Terminal Base		Alloy	J-STD-020 MSL Rating		Peak Process Body Temperature		e Max Time at Peak Temper		ture N	lumber of	Reflow Cyc	les		
Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)		no CU Alloy	CU Alloy 1			260		C 30		secor	nds 3				
Comments						·									
evel 1 - maximum time at pea	ak temperature duri	ing soldering is 10	30 seconds												
or more information regard	ing material compos	sition please refer	to page 3												

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	toHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl hthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and co for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	on above	Supplier Acceptance	* Accepted							
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	stislav Drska	Le									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.3	mg	Supplier	Silicon (Si)	7440-21-3		0.3	mg
Die Attach Epoxy	0.1	mg	Supplier	Poly(oxypropylene)diamine	9046-10-0		0.003	mg
			Supplier	Silver (Ag)	7440-22-4		0.085	mg
			Supplier	Proprietary	Proprietary Data		0.005	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.007	mg
Lead Frame	6.43	mg	Supplier	Zinc (Zn)	7440-66-6		0.0077	mg
			Supplier	Iron (Fe)	7439-89-6		0.1511	mg
			Supplier	Copper (Cu)	7440-50-8		6.2692	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0019	mg
Mold Compound-Black	5.6	mg		Epoxy resin	proprietary data		0.28	mg
			Supplier	Phenolic Resin	Proprietary Data		0.112	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.14	mg
			Supplier	Carbon Black (C)	1333-86-4		0.028	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		5.04	mg
Plating	0.07	mg	Supplier	Palladium (Pd)	7440-05-3		0.0017	mg
			В	Nickel (Ni)	7440-02-0		0.0616	mg
			Supplier	Gold (Au)	7440-57-5		0.0067	mg
Wire Bond - Cu	0.02	mg	Supplier	Palladium (Pd)	7440-05-3		0.0004	mg
			Supplier	Gold (Au)	7440-57-5		0	mg
			Supplier	Copper (Cu)	7440-50-8		0.0196	mg